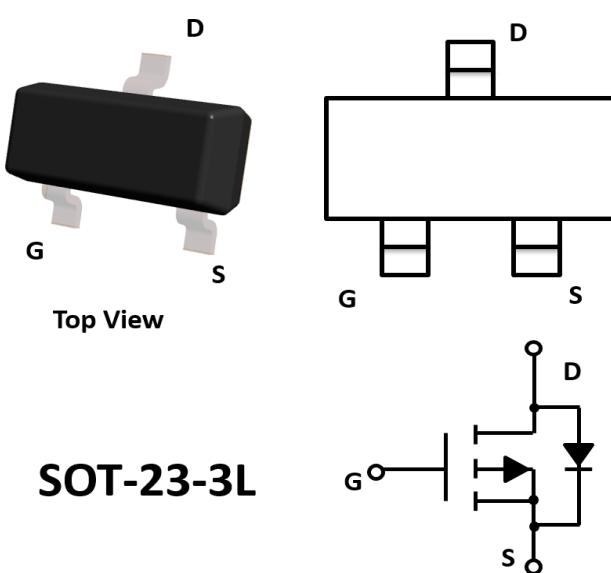


P-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} -20V
- I_D -5.0A
- $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) <30 mohm
- $R_{DS(ON)}$ (at $V_{GS}=-2.5V$) <40 mohm
- $R_{DS(ON)}$ (at $V_{GS}=1.8V$) <56 mohm

General Description

- Trench Power LV MOSFET technology
- High Density Cell Design for Low $R_{DS(ON)}$
- High Speed switching

Applications

- Battery protection
- Load switch
- Power management

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-source Voltage	V_{DS}	-20	V
Gate-source Voltage	V_{GS}	± 10	V
Drain Current	I_D	-5.0	A
Pulsed Drain Current ^A	I_{DM}	-20	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$ Steady State	P_D	1.2	W
Thermal Resistance Junction-to-Ambient @ Steady State ^B	$R_{\theta JA}$	104	$^\circ\text{C} / \text{W}$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^\circ\text{C}$

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
HAS20P7L	F2		3000	15000	180000	7" reel

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-18\text{V}, V_{\text{GS}}=0\text{V}, T_c=25^\circ\text{C}$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 10\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}= V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.4	-0.7	-1.0	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}= -4.5\text{V}, I_{\text{D}}=-5\text{A}$		25	30	$\text{m}\Omega$
		$V_{\text{GS}}= -2.5\text{V}, I_{\text{D}}=-3\text{A}$		32	40	
		$V_{\text{GS}}= -1.8\text{V}, I_{\text{D}}=-1\text{A}$		45	56	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=-5.7\text{A}, V_{\text{GS}}=0\text{V}$		-0.8	-1.2	V
Maximum Body-Diode Continuous Current	I_{S}				-5	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-4\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		740		pF
Output Capacitance	C_{oss}			290		
Reverse Transfer Capacitance	C_{rss}			190		
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=-2.5\text{V}, V_{\text{DS}}=-4\text{V}, I_{\text{D}}=-4\text{A}$		4.5		nC
Gate Source Charge	Q_{gs}			1.2		
Gate Drain Charge	Q_{gd}			1.6		
Turn-on Delay Time	$t_{\text{D(on)}}$	$V_{\text{GEN}}=-8\text{V}, V_{\text{DD}}=-4\text{V}, R_{\text{L}}=1.2\Omega, I_{\text{D}}=-3.3\text{A}$		5		ns
Turn-on Rise Time	t_{r}			11		
Turn-off Delay Time	$t_{\text{D(off)}}$			22		
Turn-off Fall Time	t_{f}			16		

A. Pulse Test: Pulse Width $\leqslant 300\text{us}$, Duty cycle $\leqslant 2\%$.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

■ Typical Performance Characteristics

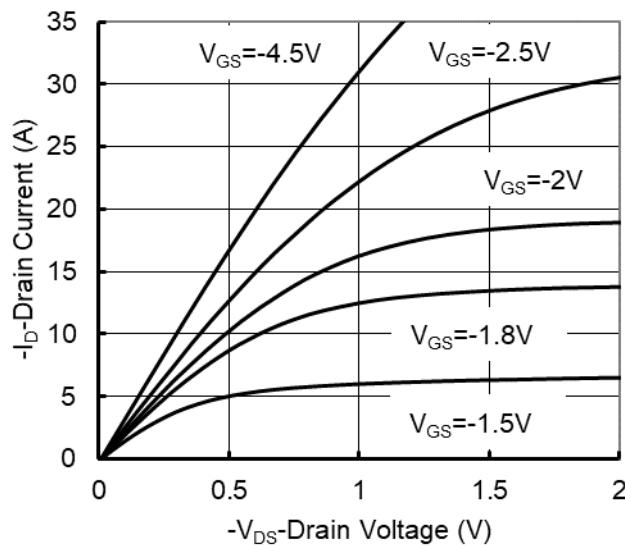


Figure 1. Output Characteristics

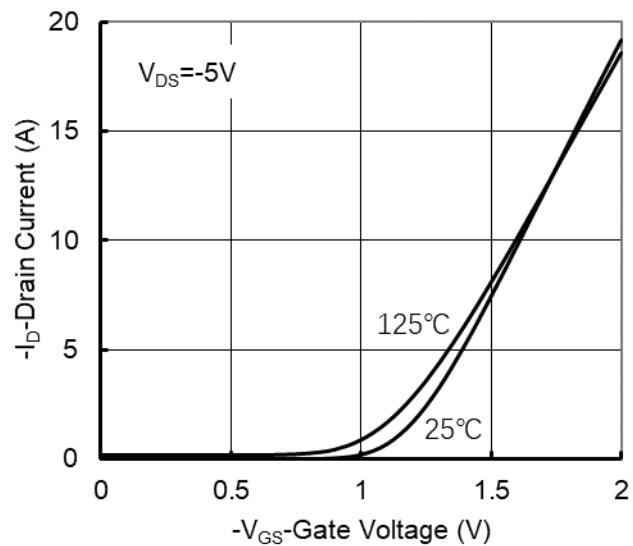


Figure 2. Transfer Characteristics

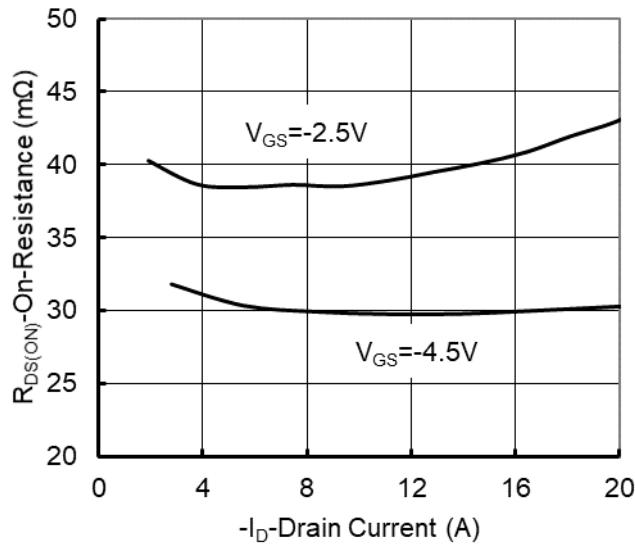


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

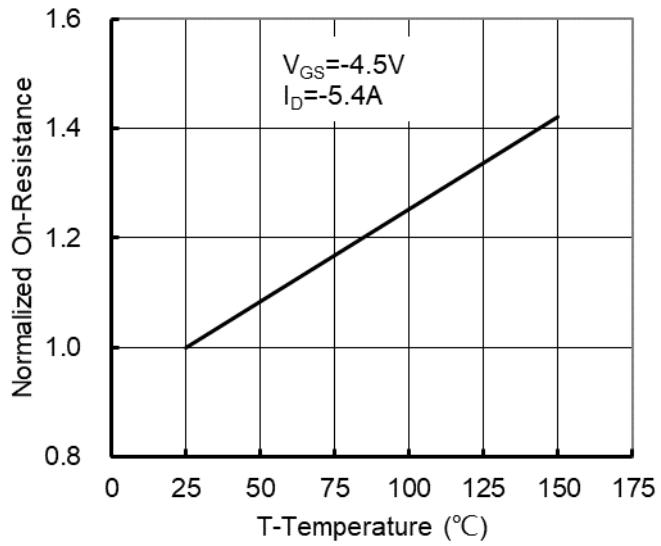


Figure 4: On-Resistance vs. Junction Temperature

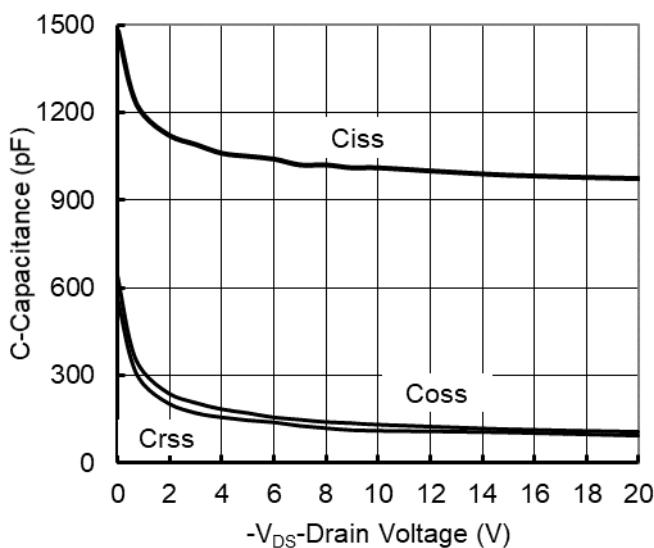


Figure 5. Capacitance Characteristics

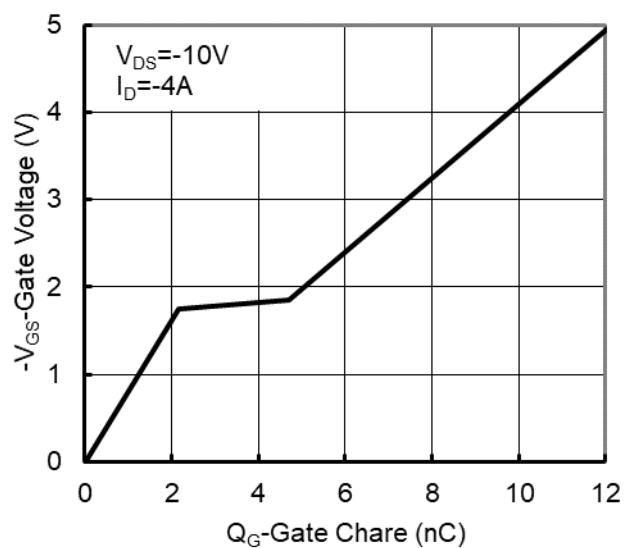


Figure 6. Gate Charge

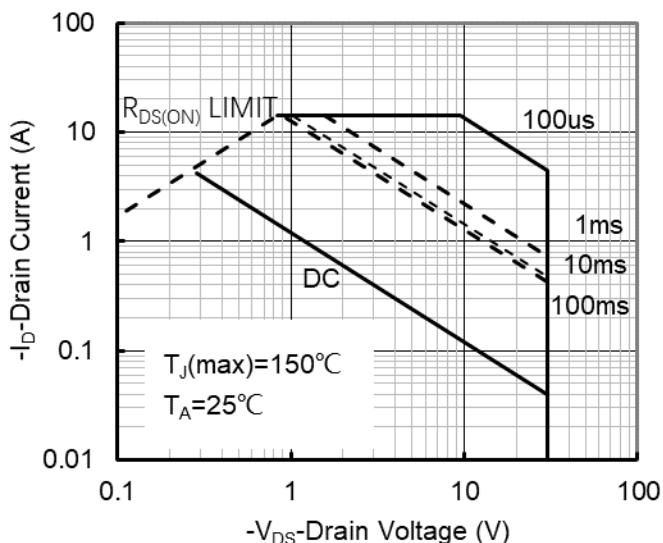


Figure7. Safe Operation Area

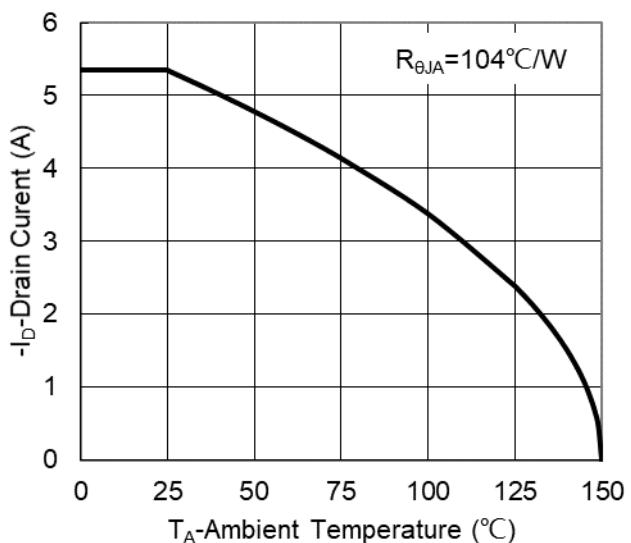
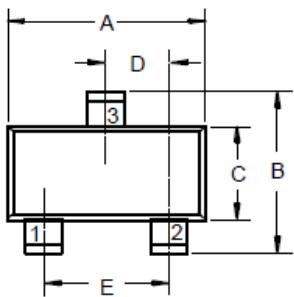


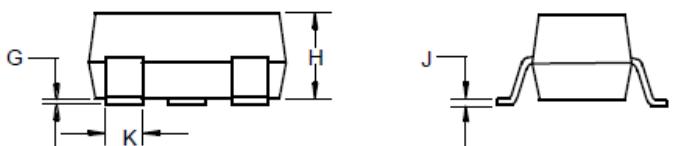
Figure8. Maximum Continuous Drain Current vs Ambient Temperature

■ SOT-23-3L Package information

SOT-23-3L



1. GATE
2. SOURCE
3. DRAIN



DIM	DIMENSIONS				NOTE	
	INCHES		MM			
	MIN	MAX	MIN	MAX		
A	.113	.117	2.87	2.97		
B	.108	.112	2.75	2.85		
C	.061	.065	1.55	1.65		
D	.036	.038	.914	.965		
E	.073	.077	1.85	1.95		
G	.0016	.0039	.04	.100		
H	.044	.049	1.12	1.25		
J	.006	.007	.14	.17		
K	.013	.015	.34	.37		

■ SOT-23-3L Suggested Pad Layout

